502209910 01/28/2013

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YUEH-SE HO	07/29/2010
YAN XUN XUE	07/29/2010

RECEIVING PARTY DATA

Name:	Alpha and Omega Semiconductor Incorporated	
Street Address:	475 Oakmead Parkway	
City:	Sunnyvale	
State/Country:	CALIFORNIA	
Postal Code:	94085	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13750944

CORRESPONDENCE DATA

Fax Number: 5106680239

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 510.668.0965
Email: josh@jdipatent.com
Correspondent Name: Joshua D. Isenberg
Address Line 1: 809 Corporate Way

Address Line 4: Fremont, CALIFORNIA 94539

ATTORNEY DOCKET NUMBER:	ANO-034/CON
NAME OF SUBMITTER:	Joshua D. Isenberg

Total Attachments: 2

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PATENT REEL: 029705 FRAME: 0330 OF \$40.00 13/50944

Attorney Docket No: ANO-034/US

ASSIGNMENT

INVENTOR AND CITY

Whereas, I, Yueh Se-Ho of 735 Iris Ave.

Sunnyvale, CA 94086

have invented:

TITLE:

WAFER LEVEL CHIP SCALE PACKAGE

SIGNED THE DECLARATION

DATE INVENTOR and executed a United States patent application therefor

on July 29, 2010. Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 12/846,743 12, filed July 29, 2010 (12) the filing date and application number of said application when known.

Whereas, Alpha and Omega Semiconductor Incorporated, a California Corporation, having its registered address at 475 Oakmead Pkwy, Sunnyvale, CA 94085, (hereinafter called AOS), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to AOS, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to AOS its successors and assigns; and I hereby agree that AOS may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when Signed and Sealed at Supplyale on July 29 , 2010

Signed and Sealed at Supplyale on July 29 , 2010

CITY AND

DATE

Docket No.: ANO-034/US

Assignment

Attorney Docket No: ANO-034/US

ASSIGNMENT

INVENTOR AND CITY

Whereas, I, Yan Xun Xue of 224 Carlester Dr.

Los Gatos, CA 95032

have invented:

TITLE:

WAFER LEVEL CHIP SCALE PACKAGE

SIGNED THE

DECLARATION

DATE INVENTOR and executed a United States patent application therefor

on) uly 29 ____, 2010. Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 12/846,743 J. filed July 29, 2010 J. the filing date and application number of said application when known.

Whereas, Alpha and Omega Semiconductor Incorporated, a California Corporation, having its registered address at 475 Oakmead Pkwy, Sunnyvale, CA 94085, (hereinafter called AOS), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to AOS, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to AOS its successors and assigns; and I hereby agree that AOS may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND

Signed and Sealed at <u>Sumny vale</u> on <u>7/29/2010</u>, 2010

DATE

SIGNATURE OF INVENTOR

Docket No.: ANO-034/US

Assignment

PATENT REEL: 029705 FRAME: 0332

RECORDED: 01/28/2013